

## Description

### PECJ N-channel Enhancement Mode Power MOSFET

#### Features

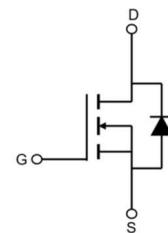
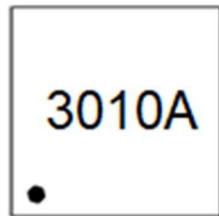
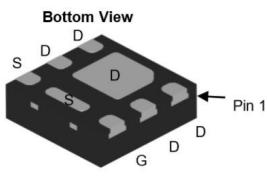
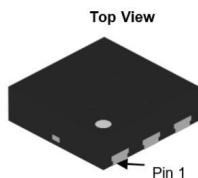
- 30V, 20A  
 $R_{DS(ON)} < 10m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(ON)} < 17m\Omega$  @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

- Load Switch
- PWM Application
- Power management



100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



PDFN2X2-6L

Marking and pin Assignment

Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
3010A	PECJ3010A	TAPING	PDFN2X2-6L	7inch	3000	180000

## Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		30	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	20	A
		$T_C = 100^\circ C$	13	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		80	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		16	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ C$	6.2	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		20	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	30	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$	-	7.5	10	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	-	11.5	17	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	900	-	pF
$C_{oss}$	Output Capacitance		-	140	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	120	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=15\text{V}$ , $I_D=20\text{A}$ , $V_{GS}=10\text{V}$	-	19	-	nC
$Q_{gs}$	Gate-Source Charge		-	6.3	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	4.5	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}$ , $I_D=10\text{A}$ , $R_{\text{GEN}}=3\Omega$ , $V_{GS}=10\text{V}$	-	6	-	ns
$t_r$	Turn-on Rise Time		-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	25	-	ns
$t_f$	Turn-off Fall Time		-	7	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	20	-	A
$I_{sM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	80	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=20\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	7	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	6.3	-	nC

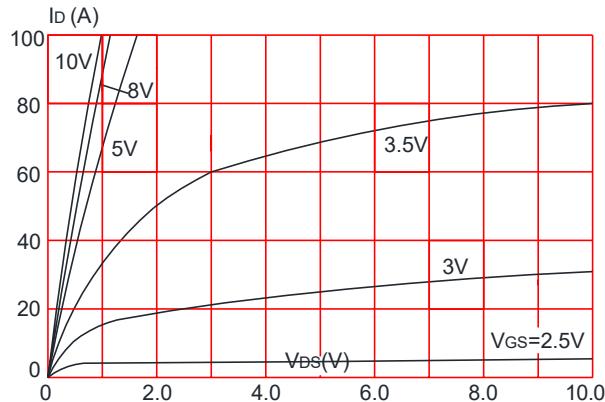
Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{GS}=10\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$

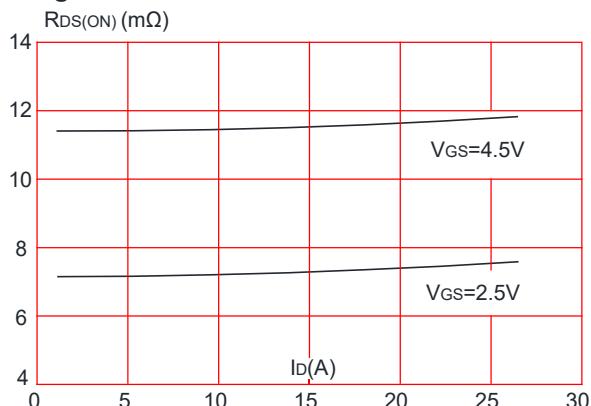
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

## Typical Performance Characteristics

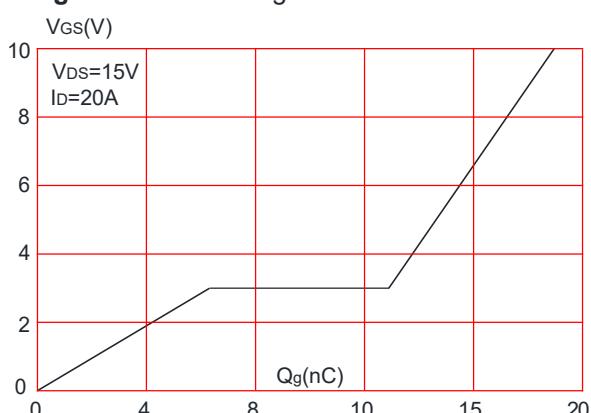
**Figure 1:** Output Characteristics



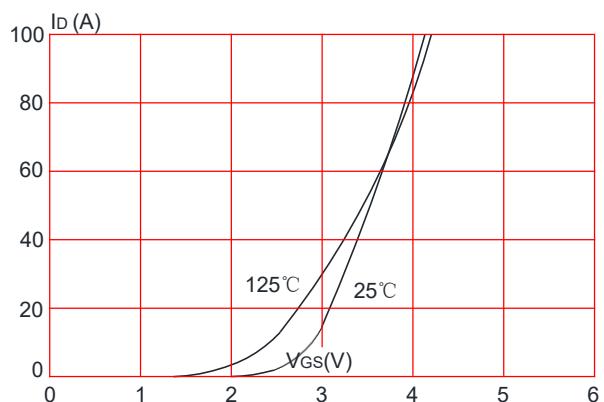
**Figure 3:** On-resistance vs. Drain Current



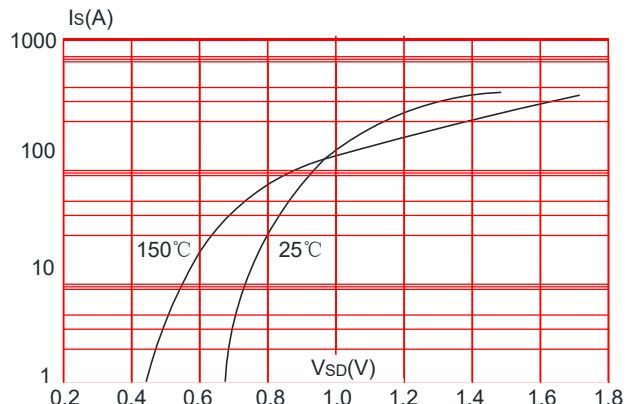
**Figure 5: Gate Charge Characteristics**



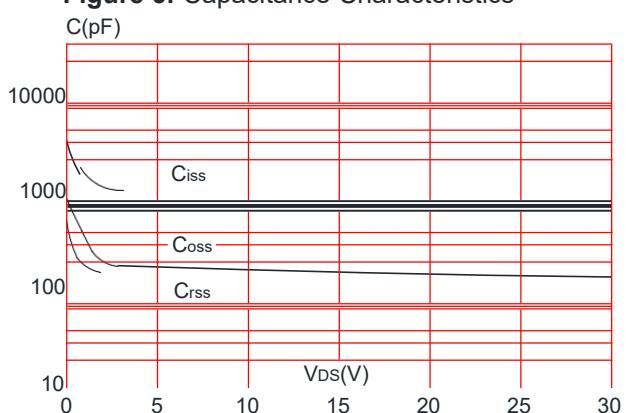
**Figure 2:** Typical Transfer Characteristics



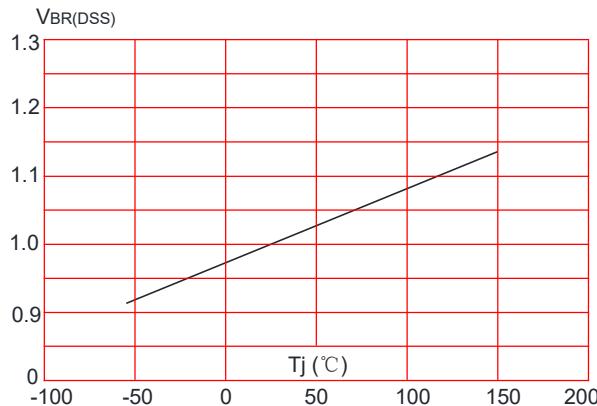
**Figure 4:** Body Diode Characteristics



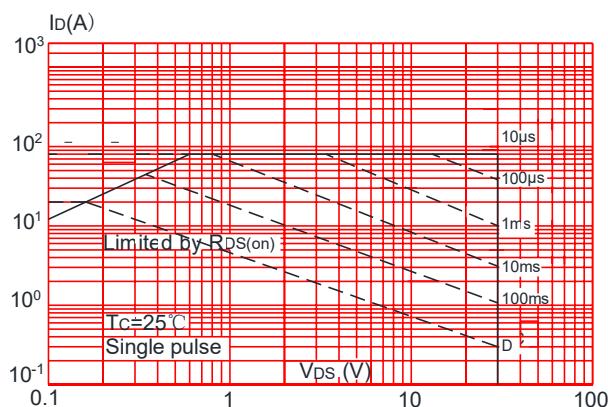
**Figure 6: Capacitance Characteristics**



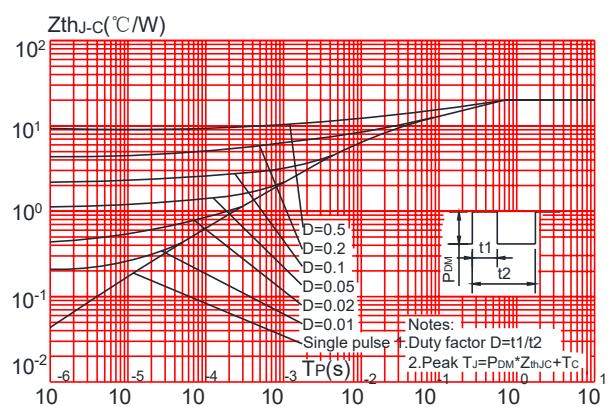
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



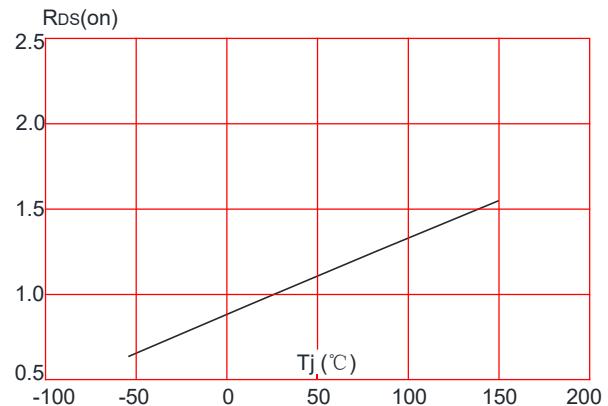
**Figure 9:** Maximum Safe Operating Area



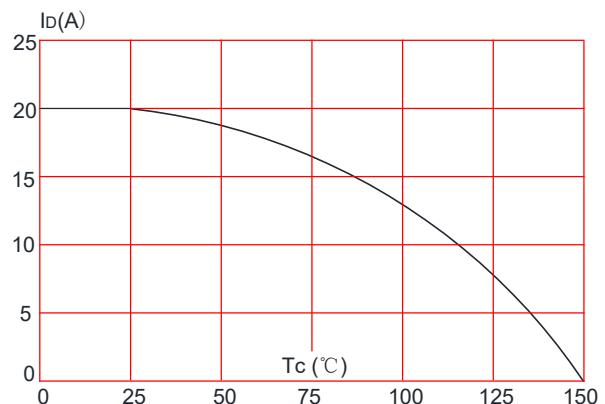
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



## Test Circuit

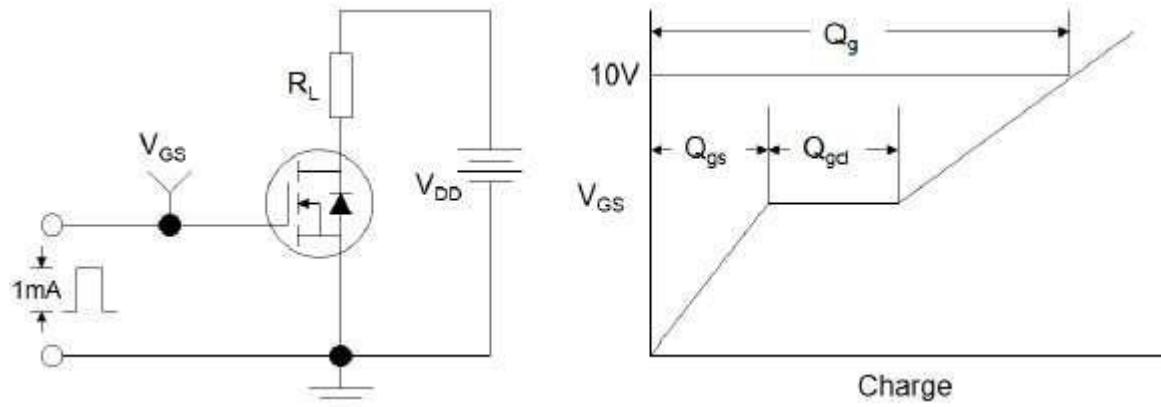


Figure 1: Gate Charge Test Circuit & Waveform

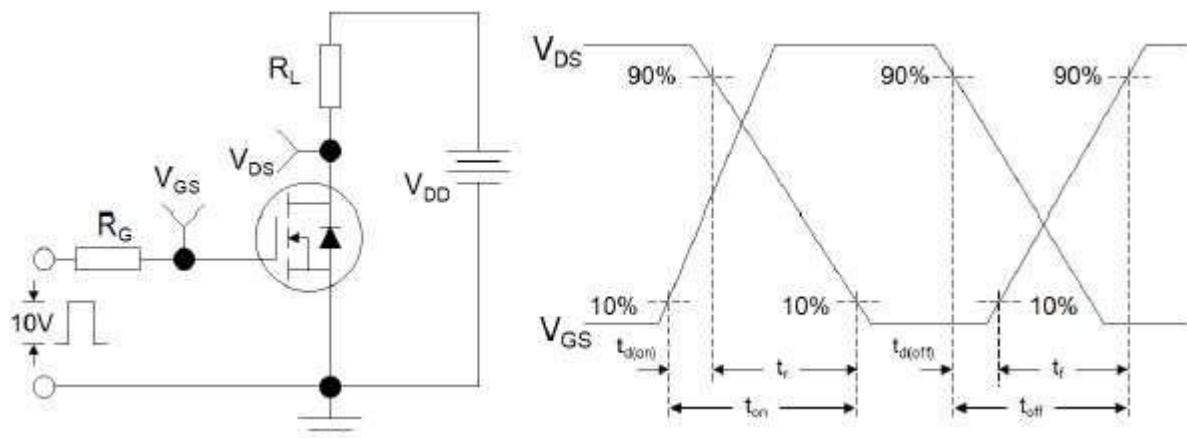


Figure 2: Resistive Switching Test Circuit & Waveforms

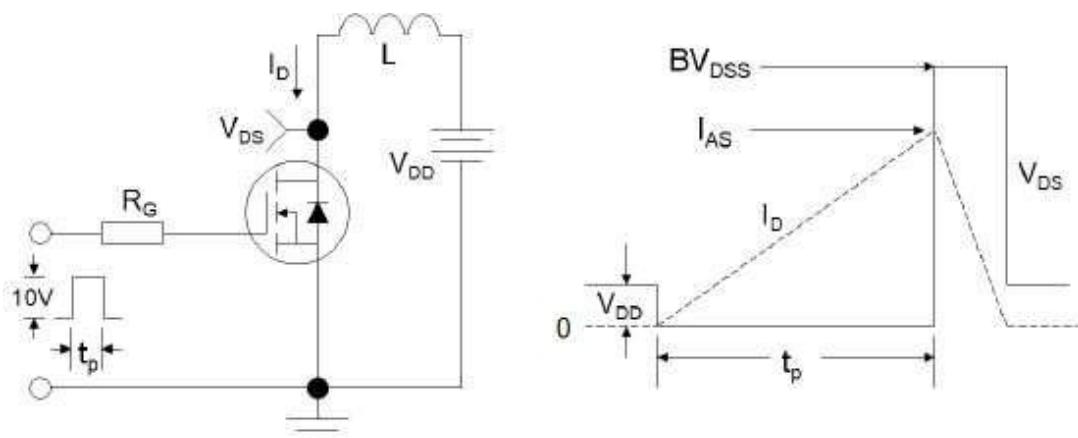
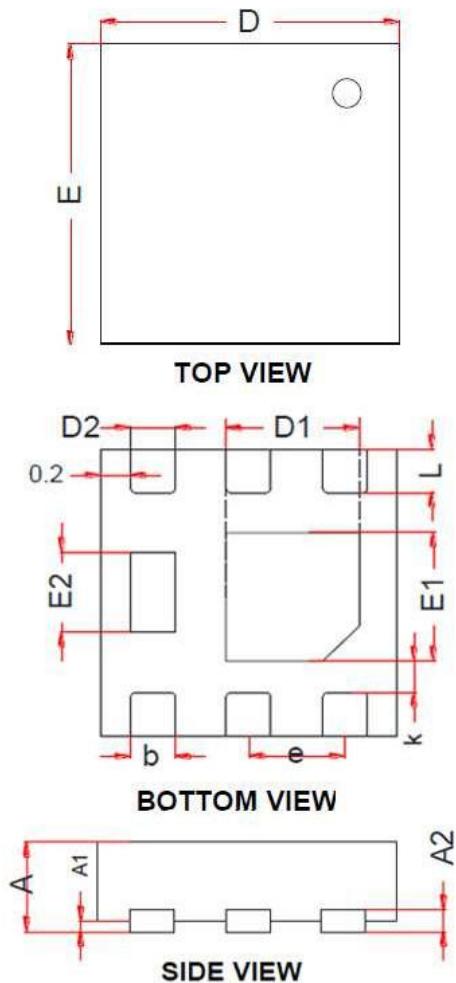


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

## Package Mechanical Data- PDFN2X2-6L



Symbol	Dimensions in millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.85
A1	0.00	0.02	0.05
A2	0.20Ref.		
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D1	0.85	0.90	0.95
D2	0.25	0.30	0.35
E	1.95	2.00	2.05
E1	0.75	0.80	0.85
E2	0.56Ref.		
e	0.65BSC.		
L	0.30	0.35	0.40
K	0.20	-	-